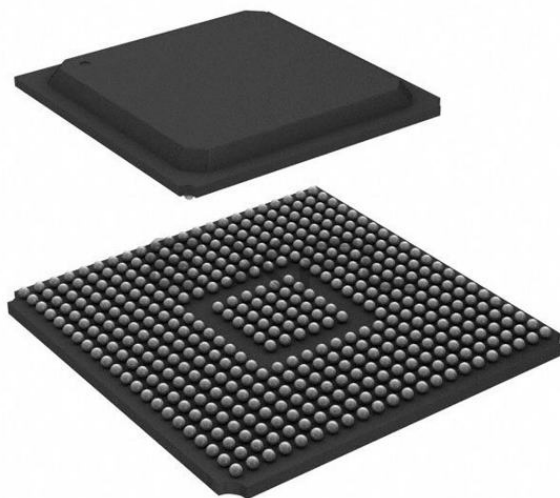




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	752
Number of Logic Elements/Cells	6768
Total RAM Bits	516096
Number of I/O	248
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	456-BBGA
Supplier Device Package	456-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp4-6fg456i

Virtex-II Pro Ordering Examples

Virtex-II Pro ordering examples are shown in **Figure 1** (flip-chip package) and **Figure 2** (Pb-free wire-bond package).

Example: XC2VP40 -7 FF 1152 C

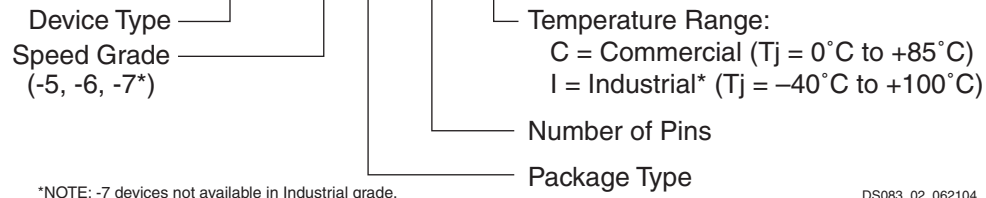


Figure 1: Virtex-II Pro Ordering Example, Flip-Chip Package

Example: XC2VP40 -6 FG G 676 I

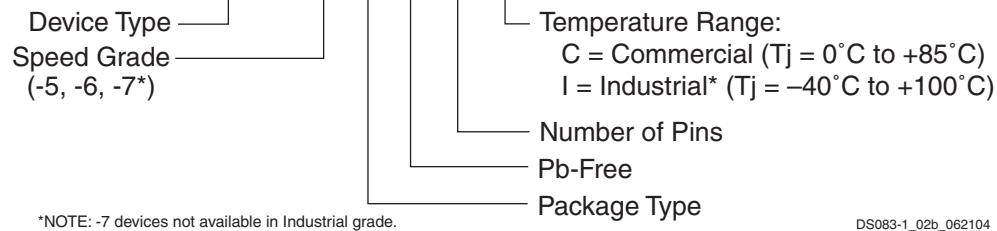


Figure 2: Virtex-II Pro Ordering Example, Pb-Free Wire-Bond Package

Virtex-II Pro X Ordering Example

A Virtex-II Pro X ordering example is shown in **Figure 3**.

Example: XC2VPX20 -6 FF 896 C

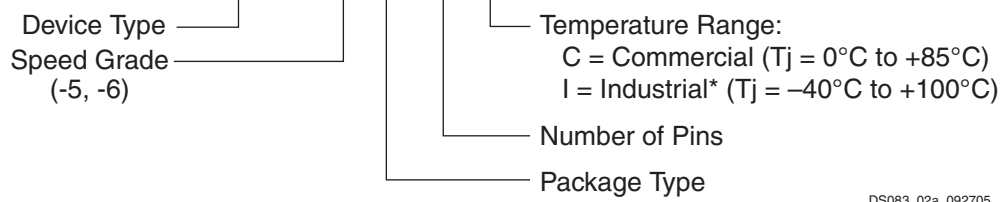


Figure 3: Virtex-II Pro X Ordering Example, Flip-Chip Package

cation is given at the receiver interface. The realignment indicator is a distinct output.

The transceiver continuously monitors the data for the presence of the 10-bit character(s). Upon each occurrence of a 10-bit character, the data is checked for word alignment. If comma detect is disabled, the data is not aligned to any particular pattern. The programmable option allows a user to align data on comma+, comma–, both, or a unique user-defined and programmed sequence.

Comma detection has been expanded beyond 10-bit symbol detection and alignment to include 8-bit symbol detection and alignment for 16-, 20-, 32-, and 40-bit paths. The ability to detect symbols, and then either align to 1-word, 2-word, or 4-word boundaries is included. The RXSLIDE input allows the user to “slide” or “slip” the alignment by one bit in each 16-, 20-, 32- and 40-bit mode at any time for SONET applications. Comma detection can be bypassed when needed.

Clock Correction

RXRECCLK (the recovered clock) reflects the data rate of the incoming data. RXUSRCLK defines the rate at which the FPGA fabric consumes the data. Ideally, these rates are identical. However, since the clocks typically have different sources, one of the clocks will be faster than the other. The receiver buffer accommodates this difference between the clock rates. See [Figure 6](#).

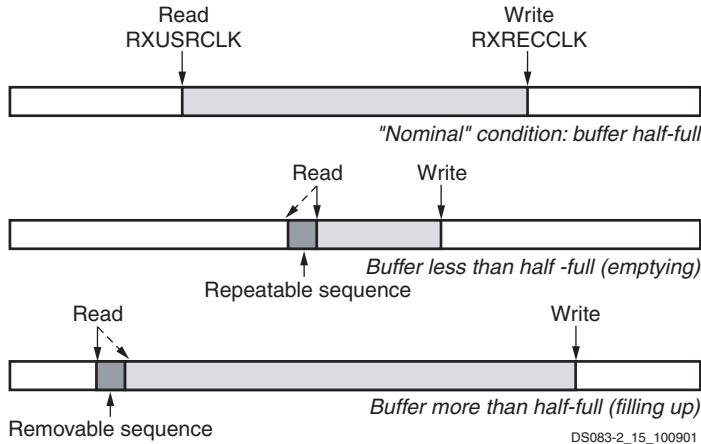


Figure 6: Clock Correction in Receiver

Nominally, the buffer is always half full. This is shown in the top buffer, [Figure 6](#), where the shaded area represents buffered data not yet read. Received data is inserted via the write pointer under control of RXRECCLK. The FPGA fabric reads data via the read pointer under control of RXUSRCLK. The half full/half empty condition of the buffer gives a cushion for the differing clock rates. This operation continues indefinitely, regardless of whether or not “meaningful” data is being received. When there is no meaningful data to be received, the incoming data will consist of IDLE characters or other padding.

If RXUSRCLK is faster than RXRECCLK, the buffer becomes more empty over time. The clock correction logic corrects for this by decrementing the read pointer to reread a repeatable byte sequence. This is shown in the middle buffer, [Figure 6](#), where the solid read pointer decrements to the value represented by the dashed pointer. By decrementing the read pointer instead of incrementing it in the usual fashion, the buffer is partially refilled. The transceiver design will repeat a single repeatable byte sequence when necessary to refill a buffer. If the byte sequence length is greater than one, and if attribute CLK_COR_REPEAT_WAIT is 0, then the transceiver may repeat the same sequence multiple times until the buffer is refilled to the desired extent.

Similarly, if RXUSRCLK is slower than RXRECCLK, the buffer will fill up over time. The clock correction logic corrects for this by incrementing the read pointer to skip over a removable byte sequence that need not appear in the final FPGA fabric byte stream. This is shown in the bottom buffer, [Figure 6](#), where the solid read pointer increments to the value represented by the dashed pointer. This accelerates the emptying of the buffer, preventing its overflow. The transceiver design will skip a single byte sequence when necessary to partially empty a buffer. If attribute CLK_COR_REPEAT_WAIT is 0, the transceiver may also skip two consecutive removable byte sequences in one step to further empty the buffer when necessary.

These operations require the clock correction logic to recognize a byte sequence that can be freely repeated or omitted in the incoming data stream. This sequence is generally an IDLE sequence, or other sequence comprised of special values that occur in the gaps separating packets of meaningful data. These gaps are required to occur sufficiently often to facilitate the timely execution of clock correction.

Channel Bonding

Some gigabit I/O standards such as Infiniband specify the use of multiple transceivers in parallel for even higher data rates. Words of data are split into bytes, with each byte sent over a separate channel (transceiver). See [Figure 7](#).

The top half of the figure shows the transmission of words split across four transceivers (channels or lanes). PPPP, QQQQ, RRRR, SSSS, and TTTT represent words sent over the four channels.

The bottom-left portion of [Figure 7](#) shows the initial situation in the FPGA’s receivers at the other end of the four channels. Due to variations in transmission delay—especially if the channels are routed through repeaters—the FPGA fabric might not correctly assemble the bytes into complete words. The bottom-left illustration shows the incorrect assembly of data words PQPP, QRQQ, RSRR, and so forth.

To support correction of this misalignment, the data stream includes special byte sequences that define corresponding points in the several channels. In the bottom half of [Figure 7](#), the shaded “P” bytes represent these special characters. Each receiver recognizes the “P” channel bond-

18-Bit x 18-Bit Multipliers

Introduction

A Virtex-II Pro multiplier block is an 18-bit by 18-bit 2's complement signed multiplier. Virtex-II Pro devices incorporate many embedded multiplier blocks. These multipliers can be associated with an 18 Kb block SelectRAM+ resource or can be used independently. They are optimized for high-speed operations and have a lower power consumption compared to an 18-bit x 18-bit multiplier in slices.

Each SelectRAM+ memory and multiplier block is tied to four switch matrices, as shown in Figure 53.

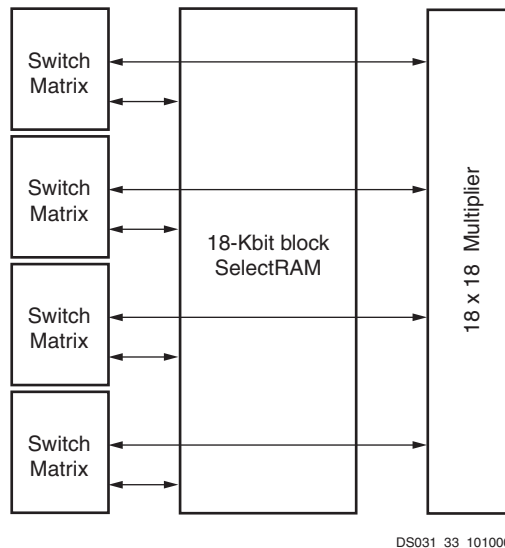


Figure 53: SelectRAM+ and Multiplier Blocks

Association With Block SelectRAM+ Memory

The interconnect is designed to allow SelectRAM+ memory and multiplier blocks to be used at the same time, but some interconnect is shared between the SelectRAM+ and the multiplier. Thus, SelectRAM+ memory can be used only up to 18 bits wide when the multiplier is used, because the multiplier shares inputs with the upper data bits of the SelectRAM+ memory.

This sharing of the interconnect is optimized for an 18-bit-wide block SelectRAM+ resource feeding the multiplier. The use of SelectRAM+ memory and the multiplier with an accumulator in LUTs allows for implementation of a digital signal processor (DSP) multiplier-accumulator (MAC) function, which is commonly used in finite and infinite impulse response (FIR and IIR) digital filters.

Configuration

The multiplier block is an 18-bit by 18-bit signed multiplier (2's complement). Both A and B are 18-bit-wide inputs, and the output is 36 bits. Figure 54 shows a multiplier block.

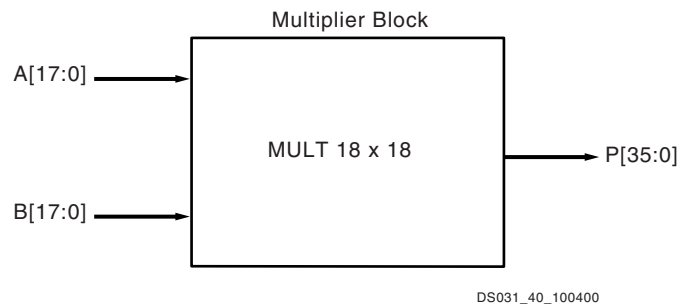


Figure 54: Multiplier Block

Locations / Organization

Multiplier organization is identical to the 18 Kb SelectRAM+ organization, because each multiplier is associated with an 18 Kb block SelectRAM+ resource.

Table 26: Multiplier Resources

Device	Columns	Total Multipliers
XC2VP2	4	12
XC2VP4	4	28
XC2VP7	6	44
XC2VP20	8	88
XC2VP30	8	136
XC2VPX20	8	88
XC2VP40	10	192
XC2VP50	12	232
XC2VP70	14	328
XC2VPX70	14	308
XC2VP100	16	444

In addition to the built-in multiplier blocks, the CLB elements have dedicated logic to implement efficient multipliers in logic. (Refer to Configurable Logic Blocks (CLBs), page 35).

Global Clock Multiplexer Buffers

Virtex-II Pro devices have 16 clock input pins that can also be used as regular user I/Os. Eight clock pads center on both the top edge and the bottom edge of the device, as illustrated in Figure 55.

The global clock multiplexer buffer represents the input to dedicated low-skew clock tree distribution in Virtex-II Pro devices. Like the clock pads, eight global clock multiplexer buffers are on the top edge of the device and eight are on the bottom edge.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device initialization. The actual current consumed depends on the power-on ramp rate of the power supply.

The V_{CCINT} power supply must ramp on, monotonically, no faster than 200 μ s and no slower than 50 ms. Ramp-on is defined as: 0 V_{DC} to minimum supply voltages (see [Table 2](#)).

V_{CCAUX} and V_{CCO} can power on at any ramp rate. Power supplies can be turned on in any sequence.

[Table 5](#) shows the minimum current required by Virtex-II Pro devices for proper power-on and configuration.

If the current minimums shown in [Table 5](#) are met, the device powers on properly after all three supplies have passed through their power-on reset threshold voltages.

Once initialized and configured, use the power calculator to estimate current drain on these supplies.

For more information on V_{CCAUX} , V_{CCO} , and configuration mode, refer to Chapter 3 in the *Virtex-II Pro Platform FPGA User Guide*.

Table 5: Power-On Current for Virtex-II Pro Devices

Symbol	Device											Units
	XC2VP2	XC2VP4	XC2VP7	XC2VP20	XC2VPX20	XC2VP30	XC2VP40	XC2VP50	XC2VP70	XC2VPX70	XC2VP100	
$I_{CCINTMIN}$	500	500	500	600	600	800	1050	1250	1700	1700	2200	mA
$I_{CCAUXMIN}$	250	250	250	250	250	250	250	250	250	250	250	mA
I_{CCOMIN}	100	100	100	100	100	100	100	100	100	100	100	mA

Notes:

1. Power-on current parameter values are specified for Commercial Grade. For Industrial Grade values, multiply Commercial Grade values by 1.5.
2. I_{CCOMIN} values listed here apply to the entire device (all banks).

General Power Supply Requirements

Proper decoupling of all FPGA power supplies is essential. Consult Xilinx Application Note [XAPP623](#) for detailed information on power distribution system design.

V_{CCAUX} powers critical resources in the FPGA. Therefore, this supply voltage is especially susceptible to power supply noise. V_{CCAUX} can share a power plane with V_{CCO} , but only if V_{CCO} does not have excessive noise. Staying within simultaneously switching output (SSO) limits is essential for keeping power supply noise to a minimum. Refer to

[XAPP689](#), "Managing Ground Bounce in Large FPGAs," to determine the number of simultaneously switching outputs allowed per bank at the package level.

Changes in V_{CCAUX} voltage beyond 200 mV peak-to-peak should take place at a rate no faster than 10 mV per millisecond.

Recommended practices that can help reduce jitter and period distortion are described in Xilinx Answer Record 13756.

Master/Slave Serial Mode Parameters

Clock timing for Slave Serial configuration programming is shown in **Figure 8**, with Master Serial clock timing shown in **Figure 9**. Programming parameters for both Slave and Master modes are given in **Table 50**.

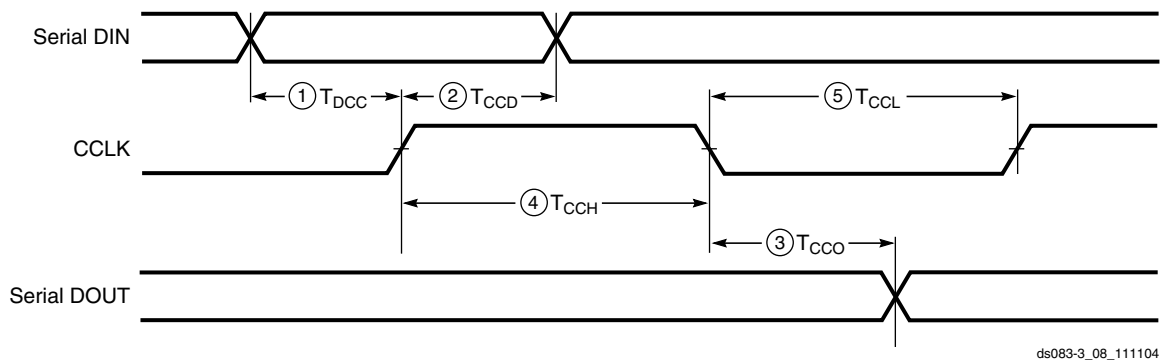


Figure 8: Slave Serial Mode Timing Sequence

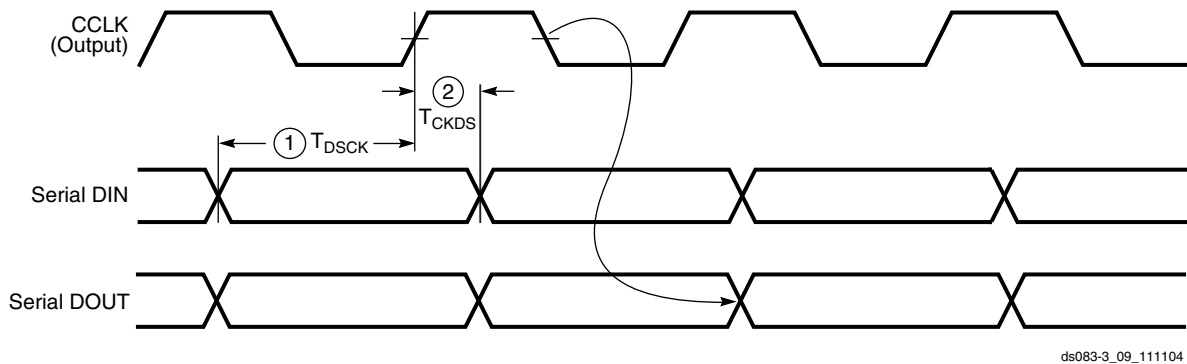


Figure 9: Master Serial Mode Timing Sequence

Table 50: Master/Slave Serial Mode Timing Characteristics

	Description	Figure References	Symbol	Value	Units
CCLK	DIN setup/hold, slave mode (Figure 8)	1/2	T_{DCC}/T_{CCD}	5.0/0.0	ns, min
	DIN setup/hold, master mode (Figure 9)	1/2	T_{DSCK}/T_{CKDS}	5.0/0.0	ns, min
	DOUT	3	T_{CCO}	12.0	ns, max
	High time	4	T_{CCH}	5.0	ns, min
	Low time	5	T_{CCL}	5.0	ns, min
	Maximum start-up frequency		$F_{CC_STARTUP}$	50	MHz, max
	Maximum frequency		F_{CC_SERIAL}	66 ⁽¹⁾	MHz, max
	Frequency tolerance, master mode with respect to nominal			+45% -30%	

Notes:

1. If no provision is made in the design to adjust the frequency of CCLK, F_{CC_SERIAL} should not exceed $F_{CC_STARTUP}$.

FF672 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)

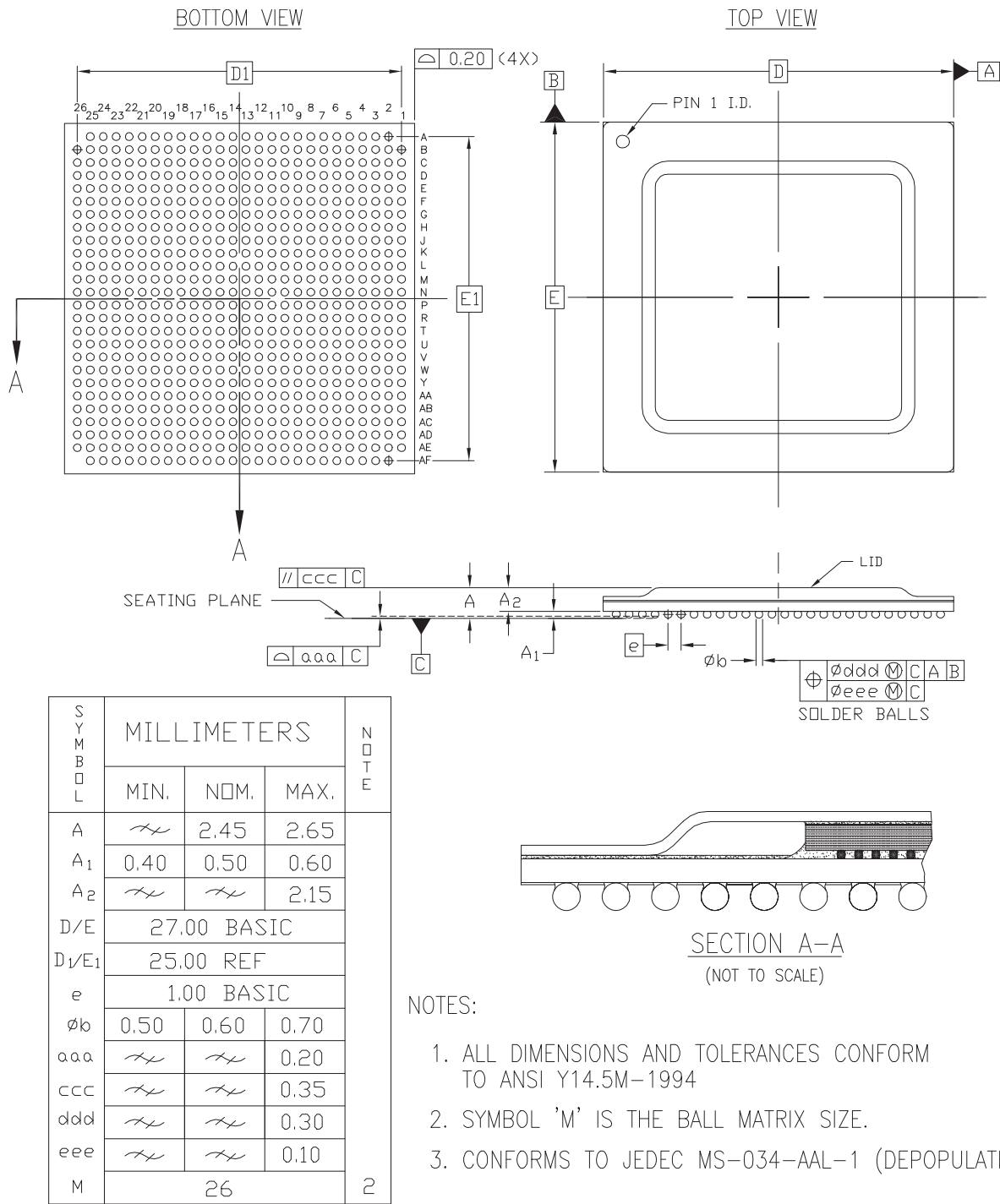


Figure 4: FF672 Flip-Chip Fine-Pitch BGA Package Specifications

FF896 Flip-Chip Fine-Pitch BGA Package

As shown in Table 9, XC2VP7, XC2VP20, and XC2VP30 Virtex-II Pro devices are available in the FF896 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for differences shown in the "No Connects" column. Following this table are the **FF896 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)**.

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
3	IO_L39P_3		AE2	NC		
3	IO_L38N_3		AA7	NC		
3	IO_L38P_3		AA8	NC		
3	IO_L37N_3		AD3	NC		
3	IO_L37P_3		AD4	NC		
3	IO_L36N_3		AF1	NC		
3	IO_L36P_3		AF2	NC		
3	IO_L35N_3		AC5	NC		
3	IO_L35P_3		AC6	NC		
3	IO_L34N_3		AF3	NC		
3	IO_L34P_3		AF4	NC		
3	IO_L33N_3/VREF_3		AE3	NC		
3	IO_L33P_3		AE4	NC		
3	IO_L32N_3		AB7	NC		
3	IO_L32P_3		AB8	NC		
3	IO_L31N_3		AE5	NC		
3	IO_L31P_3		AF6	NC		
3	IO_L06N_3		AG1			
3	IO_L06P_3		AG2			
3	IO_L05N_3		AD5			
3	IO_L05P_3		AD6			
3	IO_L04N_3		AG3			
3	IO_L04P_3		AH4			
3	IO_L03N_3/VREF_3		AH1			
3	IO_L03P_3		AH2			
3	IO_L02N_3		AG5			
3	IO_L02P_3		AH5			
3	IO_L01N_3/VRP_3		AJ3			
3	IO_L01P_3/VRN_3		AK3			
4	IO_L01N_4/BUSY/DOUT ⁽¹⁾		AG6			
4	IO_L01P_4/INIT_B		AF7			
4	IO_L02N_4/D0/DIN ⁽¹⁾		AC9			
4	IO_L02P_4/D1		AD9			
4	IO_L03N_4/D2		AG7			
4	IO_L03P_4/D3		AH7			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	VCCO_4		AA11			
4	VCCO_4		AA10			
5	VCCO_5		AB21			
5	VCCO_5		AB20			
5	VCCO_5		AB19			
5	VCCO_5		AB18			
5	VCCO_5		AA21			
5	VCCO_5		AA20			
5	VCCO_5		AA19			
5	VCCO_5		AA18			
5	VCCO_5		AA17			
5	VCCO_5		AA16			
6	VCCO_6		AB22			
6	VCCO_6		AA22			
6	VCCO_6		Y22			
6	VCCO_6		Y21			
6	VCCO_6		W22			
6	VCCO_6		W21			
6	VCCO_6		V22			
6	VCCO_6		V21			
6	VCCO_6		U21			
6	VCCO_6		T21			
7	VCCO_7		R21			
7	VCCO_7		P21			
7	VCCO_7		N22			
7	VCCO_7		N21			
7	VCCO_7		M22			
7	VCCO_7		M21			
7	VCCO_7		L22			
7	VCCO_7		L21			
7	VCCO_7		K22			
7	VCCO_7		J22			
N/A	CCLK		AC7			
N/A	PROG_B		G24			
N/A	DONE		AC8			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	GND		AG19			
N/A	GND		AG12			
N/A	GND		AG9			
N/A	GND		AG4			
N/A	GND		AF26			
N/A	GND		AF5			
N/A	GND		AE25			
N/A	GND		AE18			
N/A	GND		AE13			
N/A	GND		AE6			
N/A	GND		AC30			
N/A	GND		AC1			
N/A	GND		Y28			
N/A	GND		Y25			
N/A	GND		Y20			
N/A	GND		Y11			
N/A	GND		Y6			
N/A	GND		Y3			
N/A	GND		W19			
N/A	GND		W18			
N/A	GND		W17			
N/A	GND		W16			
N/A	GND		W15			
N/A	GND		W14			
N/A	GND		W13			
N/A	GND		W12			
N/A	GND		V19			
N/A	GND		V18			
N/A	GND		V17			
N/A	GND		V16			
N/A	GND		V15			
N/A	GND		V14			
N/A	GND		V13			
N/A	GND		V12			
N/A	GND		U25			
N/A	GND		U19			

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L01P_6/VRN_6	AJ30				
6	IO_L01N_6/VRP_6	AJ31				
6	IO_L02P_6	AJ27				
6	IO_L02N_6	AJ28				
6	IO_L03P_6	AK31				
6	IO_L03N_6/VREF_6	AK32				
6	IO_L04P_6	AH29				
6	IO_L04N_6	AH30				
6	IO_L05P_6	AH27				
6	IO_L05N_6	AG28				
6	IO_L06P_6	AL33				
6	IO_L06N_6	AL34				
6	IO_L15P_6	AG29	NC			
6	IO_L15N_6/VREF_6	AG30	NC			
6	IO_L16P_6	AK33	NC			
6	IO_L16N_6	AK34	NC			
6	IO_L17P_6	AF27	NC			
6	IO_L17N_6	AF28	NC			
6	IO_L18P_6	AJ33	NC			
6	IO_L18N_6	AJ34	NC			
6	IO_L19P_6	AH31	NC			
6	IO_L19N_6	AH32	NC			
6	IO_L20P_6	AD25	NC			
6	IO_L20N_6	AD26	NC			
6	IO_L21P_6	AG31	NC			
6	IO_L21N_6/VREF_6	AG32	NC			
6	IO_L22P_6	AF29	NC			
6	IO_L22N_6	AF30	NC			
6	IO_L23P_6	AE27	NC			
6	IO_L23N_6	AE28	NC			
6	IO_L24P_6	AH33	NC			
6	IO_L24N_6	AH34	NC			
6	IO_L31P_6	AF31				
6	IO_L31N_6	AF32				
6	IO_L32P_6	AC25				
6	IO_L32N_6	AC26				
6	IO_L33P_6	AG33				
6	IO_L33N_6/VREF_6	AG34				

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L34P_6	AE30				
6	IO_L34N_6	AE31				
6	IO_L35P_6	AD27				
6	IO_L35N_6	AD28				
6	IO_L36P_6	AF33				
6	IO_L36N_6	AE33				
6	IO_L37P_6	AD29				
6	IO_L37N_6	AD30				
6	IO_L38P_6	AB25				
6	IO_L38N_6	AB26				
6	IO_L39P_6	AD31				
6	IO_L39N_6/VREF_6	AD32				
6	IO_L40P_6	AC28				
6	IO_L40N_6	AC29				
6	IO_L41P_6	AB27				
6	IO_L41N_6	AB28				
6	IO_L42P_6	AE34				
6	IO_L42N_6	AD34				
6	IO_L43P_6	AC31				
6	IO_L43N_6	AC32				
6	IO_L44P_6	AA25				
6	IO_L44N_6	AA26				
6	IO_L45P_6	AD33				
6	IO_L45N_6/VREF_6	AC33				
6	IO_L46P_6	AB29				
6	IO_L46N_6	AB30				
6	IO_L47P_6	AA27				
6	IO_L47N_6	AA28				
6	IO_L48P_6	AB31				
6	IO_L48N_6	AB32				
6	IO_L49P_6	AA29				
6	IO_L49N_6	AA30				
6	IO_L50P_6	Y25				
6	IO_L50N_6	Y26				
6	IO_L51P_6	AC34				
6	IO_L51N_6/VREF_6	AB34				
6	IO_L52P_6	AA31				
6	IO_L52N_6	AA32				

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L02P_2	D9		
2	IO_L03N_2	B7		
2	IO_L03P_2	A7		
2	IO_L04N_2/VREF_2	B6		
2	IO_L04P_2	A6		
2	IO_L05N_2	E8		
2	IO_L05P_2	D8		
2	IO_L06N_2	B4		
2	IO_L06P_2	A4		
2	IO_L07N_2	B3		
2	IO_L07P_2	A3		
2	IO_L08N_2	H7		
2	IO_L08P_2	H8		
2	IO_L09N_2	C6		
2	IO_L09P_2	C7		
2	IO_L10N_2/VREF_2	C5		
2	IO_L10P_2	B5		
2	IO_L11N_2	K8		
2	IO_L11P_2	J8		
2	IO_L12N_2	C1		
2	IO_L12P_2	C2		
2	IO_L13N_2	E7		
2	IO_L13P_2	D7		
2	IO_L14N_2	J6		
2	IO_L14P_2	J7		
2	IO_L15N_2	D5		
2	IO_L15P_2	D6		
2	IO_L16N_2/VREF_2	E4		
2	IO_L16P_2	D4		
2	IO_L17N_2	L9		
2	IO_L17P_2	K9		
2	IO_L18N_2	E3		
2	IO_L18P_2	D3		
2	IO_L19N_2	D1		
2	IO_L19P_2	D2		
2	IO_L20N_2	K7		
2	IO_L20P_2	L7		
2	IO_L21N_2	F6		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
3	IO_L28P_3	AH3		
3	IO_L27N_3/VREF_3	AJ7		
3	IO_L27P_3	AJ8		
3	IO_L26N_3	AF8		
3	IO_L26P_3	AF9		
3	IO_L25N_3	AJ5		
3	IO_L25P_3	AJ6		
3	IO_L24N_3	AJ3		
3	IO_L24P_3	AJ4		
3	IO_L23N_3	AF10		
3	IO_L23P_3	AG10		
3	IO_L22N_3	AJ1		
3	IO_L22P_3	AJ2		
3	IO_L21N_3/VREF_3	AK6		
3	IO_L21P_3	AK7		
3	IO_L20N_3	AF11		
3	IO_L20P_3	AF12		
3	IO_L19N_3	AK4		
3	IO_L19P_3	AK5		
3	IO_L18N_3	AK1		
3	IO_L18P_3	AK2		
3	IO_L17N_3	AG9		
3	IO_L17P_3	AH8		
3	IO_L16N_3	AL6		
3	IO_L16P_3	AL7		
3	IO_L15N_3/VREF_3	AK3		
3	IO_L15P_3	AL3		
3	IO_L14N_3	AG11		
3	IO_L14P_3	AH11		
3	IO_L13N_3	AL1		
3	IO_L13P_3	AL2		
3	IO_L12N_3	AM6		
3	IO_L12P_3	AM7		
3	IO_L11N_3	AH10		
3	IO_L11P_3	AJ9		
3	IO_L10N_3	AL5		
3	IO_L10P_3	AM4		
3	IO_L09N_3/VREF_3	AM2		

FF1517 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)

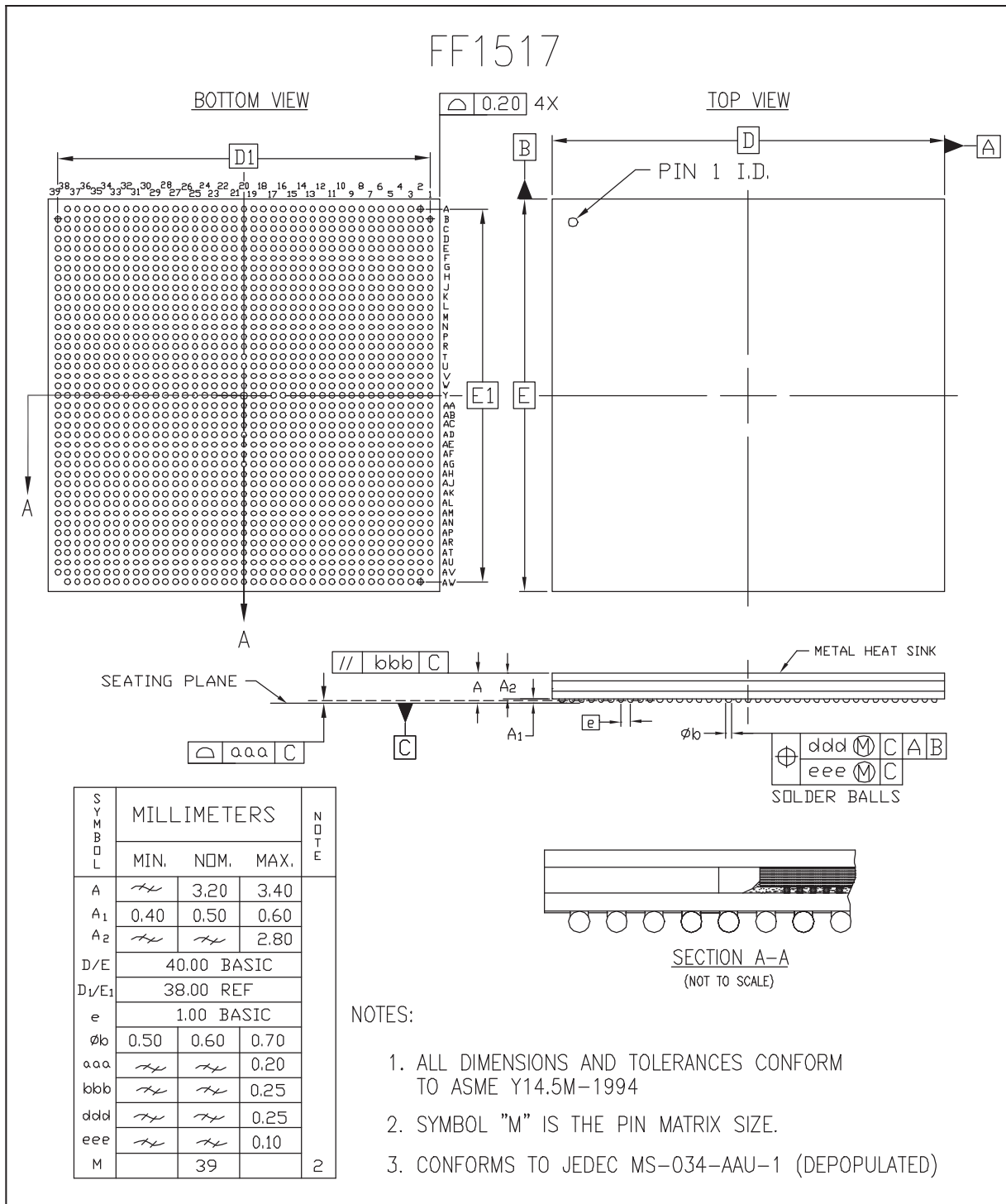


Figure 8: FF1517 Flip-Chip Fine-Pitch BGA Package Specifications

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
3	IO_L35N_3		AH11		
3	IO_L35P_3		AH12		
3	IO_L34N_3		AH5		
3	IO_L34P_3		AH6		
3	IO_L33N_3/VREF_3		AH9		
3	IO_L33P_3		AH10		
3	IO_L32N_3		AJ11		
3	IO_L32P_3		AJ12		
3	IO_L31N_3		AJ1		
3	IO_L31P_3		AJ2		
3	IO_L30N_3		AJ5		
3	IO_L30P_3		AJ6		
3	IO_L29N_3		AJ9		
3	IO_L29P_3		AJ10		
3	IO_L28N_3		AJ7		
3	IO_L28P_3		AJ8		
3	IO_L27N_3/VREF_3		AK1		
3	IO_L27P_3		AK2		
3	IO_L26N_3		AK11		
3	IO_L26P_3		AK12		
3	IO_L25N_3		AK3		
3	IO_L25P_3		AK4		
3	IO_L24N_3		AK5		
3	IO_L24P_3		AK6		
3	IO_L23N_3		AK9		
3	IO_L23P_3		AK10		
3	IO_L22N_3		AK7		
3	IO_L22P_3		AK8		
3	IO_L21N_3/VREF_3		AL2		
3	IO_L21P_3		AL3		
3	IO_L20N_3		AL11		
3	IO_L20P_3		AL12		
3	IO_L19N_3		AL4		
3	IO_L19P_3		AL5		
3	IO_L18N_3		AL7		
3	IO_L18P_3		AL8		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	TXPPAD7		A20		
N/A	GND7		C21		
N/A	RXPPAD7		A19		
N/A	RXNPAD7		A18		
N/A	VTRXPAD7		B19		
N/A	AVCCAUXRX7		B18		
N/A	AVCCAUXTX8		B16		
N/A	VTTXPAD8		B17		
N/A	TXNPAD8		A17		
N/A	TXPPAD8		A16		
N/A	GND8		C16		
N/A	RXPPAD8		A15		
N/A	RXNPAD8		A14		
N/A	VTRXPAD8		B15		
N/A	AVCCAUXRX8		B14		
N/A	AVCCAUXTX9		B12		
N/A	VTTXPAD9		B13		
N/A	TXNPAD9		A13		
N/A	TXPPAD9		A12		
N/A	GND9		C12		
N/A	RXPPAD9		A11		
N/A	RXNPAD9		A10		
N/A	VTRXPAD9		B11		
N/A	AVCCAUXRX9		B10		
N/A	AVCCAUXTX10		B8		
N/A	VTTXPAD10		B9		
N/A	TXNPAD10		A9		
N/A	TXPPAD10		A8		
N/A	GND10		C8		
N/A	RXPPAD10		A7		
N/A	RXNPAD10		A6		
N/A	VTRXPAD10		B7		
N/A	AVCCAUXRX10		B6		
N/A	AVCCAUXTX11		B4		
N/A	VTTXPAD11		B5		
N/A	TXNPAD11		A5		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	VCCINT		U26		
N/A	VCCINT		U17		
N/A	VCCINT		U16		
N/A	VCCINT		T27		
N/A	VCCINT		T26		
N/A	VCCINT		T25		
N/A	VCCINT		T24		
N/A	VCCINT		T23		
N/A	VCCINT		T22		
N/A	VCCINT		T21		
N/A	VCCINT		T20		
N/A	VCCINT		T19		
N/A	VCCINT		T18		
N/A	VCCINT		T17		
N/A	VCCINT		T16		
N/A	VCCINT		R28		
N/A	VCCINT		R27		
N/A	VCCINT		R26		
N/A	VCCINT		R17		
N/A	VCCINT		R16		
N/A	VCCINT		R15		
N/A	VCCINT		P29		
N/A	VCCINT		P28		
N/A	VCCINT		P27		
N/A	VCCINT		P16		
N/A	VCCINT		P15		
N/A	VCCINT		P14		
N/A	VCCINT		N30		
N/A	VCCINT		N13		
N/A	VCCAUX		AB42		
N/A	VCCAUX		AB41		
N/A	VCCAUX		AB2		
N/A	VCCAUX		AB1		
N/A	VCCAUX		AC42		
N/A	VCCAUX		AC1		
N/A	VCCAUX		AM32		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
1	IO_L21P_1	H13	
1	IO_L20N_1	L12	
1	IO_L20P_1	K12	
1	IO_L19N_1	B11	
1	IO_L19P_1	A11	
1	IO_L09N_1/VREF_1	E11	
1	IO_L09P_1	D11	
1	IO_L08N_1	J11	
1	IO_L08P_1	H11	
1	IO_L07N_1	G11	
1	IO_L07P_1	F11	
1	IO_L06N_1	B10	
1	IO_L06P_1	A10	
1	IO_L05_1/No_Pair	G10	
1	IO_L03N_1/VREF_1	C10	
1	IO_L03P_1	C11	
1	IO_L02N_1	L11	
1	IO_L02P_1	K11	
1	IO_L01N_1/VRP_1	F10	
1	IO_L01P_1/VRN_1	E10	
2	IO_L01N_2/VRP_2	B8	
2	IO_L01P_2/VRN_2	A8	
2	IO_L02N_2	C9	
2	IO_L02P_2	B9	
2	IO_L03N_2	B7	
2	IO_L03P_2	A7	
2	IO_L04N_2/VREF_2	B6	
2	IO_L04P_2	A6	
2	IO_L05N_2	D8	
2	IO_L05P_2	D9	
2	IO_L06N_2	B4	
2	IO_L06P_2	A4	
2	IO_L73N_2	C7	
2	IO_L73P_2	C8	
2	IO_L74N_2	G9	
2	IO_L74P_2	F9	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
3	IO_L38P_3	AE9	
3	IO_L37N_3	AH3	
3	IO_L37P_3	AJ3	
3	IO_L36N_3	AJ1	
3	IO_L36P_3	AJ2	
3	IO_L35N_3	AE6	
3	IO_L35P_3	AE7	
3	IO_L34N_3	AK6	
3	IO_L34P_3	AK7	
3	IO_L33N_3/VREF_3	AK3	
3	IO_L33P_3	AK4	
3	IO_L32N_3	AE12	
3	IO_L32P_3	AF12	
3	IO_L31N_3	AL5	
3	IO_L31P_3	AL6	
3	IO_L30N_3	AL3	
3	IO_L30P_3	AL4	
3	IO_L29N_3	AF10	
3	IO_L29P_3	AF11	
3	IO_L28N_3	AK2	
3	IO_L28P_3	AL2	
3	IO_L27N_3/VREF_3	AL7	
3	IO_L27P_3	AM6	
3	IO_L26N_3	AF7	
3	IO_L26P_3	AF8	
3	IO_L25N_3	AM4	
3	IO_L25P_3	AM5	
3	IO_L24N_3	AM1	
3	IO_L24P_3	AM2	
3	IO_L23N_3	AG10	
3	IO_L23P_3	AG11	
3	IO_L22N_3	AM7	
3	IO_L22P_3	AN7	
3	IO_L21N_3/VREF_3	AN5	
3	IO_L21P_3	AN6	
3	IO_L20N_3	AG8	
3	IO_L20P_3	AG9	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	AF1	
N/A	GND	AC1	
N/A	GND	Y1	
N/A	GND	U1	
N/A	GND	N1	
N/A	GND	J1	
N/A	GND	E1	

Notes:

1. See [Table 4](#) for an explanation of the signals available on this pin.